

AMENDMENTS TO THE CLAIMS:

Please amend Claims 22, 28, 29, 30, 41, 47, 48 and 52 as follows. Note all the claims currently pending in this application, including those not presently amended, have been reproduced below for the Examiner's convenience.

1 - 21. (Canceled)

22. (Currently Amended) A pod ~~for attachment~~ attachable to an outside surface of a grounded electromagnetic-shielded chamber, the chamber having a door and a flange portion; around the door; on the outside surface and containing a micro-device manufacturing apparatus ~~for processing a substrate~~, said pod comprising:

walls ~~for containing~~ configured to contain the substrate and having an opening; and

a lid ~~for an~~ configured to openably close the opening, ~~defined by said walls, through which the a substrate is being~~ transferred between said pod and the grounded electromagnetic-shielded chamber through the opening,

wherein said walls comprise an electromagnetic shield member, said electromagnetic shield member including a flange portion ~~for~~ configured to contacting the grounded flange portion of the ~~grounded electromagnetic-shielded~~ chamber without any intervening elements ~~being present~~ therebetween while said pod is attached to the outside surface.

23. (Previously Presented) A pod according to Claim 22, wherein said lid is arranged in front of said pod.

24. (Previously Presented) A pod according to Claim 22, wherein said lid is arranged in a bottom of said pod.

25. (Previously Presented) A pod according to Claim 22, wherein said electromagnetic shield member comprises wire mesh arranged on or within said walls.

26. (Previously Presented) A pod according to Claim 22, wherein said electromagnetic shield member comprises metal coatings arranged on said walls.

27. (Previously Presented) A pod according to Claim 22, wherein said electromagnetic shield member comprises electromagnetic-shield materials arranged in said walls.

28. (Currently Amended) A micro-device manufacturing apparatus ~~for processing a substrate, said apparatus~~ comprising:

an electromagnetic-shielded chamber, said chamber having a door and a flange portion around said door on an outside surface of said chamber;

a transfer unit arranged in said ~~electromagnetic-shielded~~ chamber; and configured to transfer ~~the~~ a substrate between said ~~electromagnetic-shielded~~ chamber and a pod, the pod being

attached to ~~an~~ the outside surface of ~~said electromagnetic-shielded chamber~~ and having an electromagnetic shield member which includes a flange portion configured to contact ~~the outside surface~~ said flange portion of said chamber; and

a processing unit; arranged in said ~~electromagnetic-shielded chamber~~; and configured to process the substrate transferred into said ~~electromagnetic-shielded chamber~~ from the pod by said transfer unit,

wherein ~~said electromagnetic-shielded chamber has a door and a grounded~~ said flange portion of said chamber is grounded, ~~around said door, on the outside surface for providing a grounded connection with~~ and configured to contact the flange portion of the pod without any intervening elements ~~being present~~ therebetween while the pod is attached to the outside surface.

29. (Currently Amended) An apparatus according to 28, wherein said transfer unit is configured to transfers the substrate between said ~~electromagnetic-shielded chamber~~ and the pod through said door.

30. (Currently Amended) An apparatus according to 28, wherein said processing unit is configured to exposes the substrate to a pattern.

31. (Previously Presented) An apparatus according to Claim 28, wherein a lid of the pod is arranged in front of the pod.

32. (Previously Presented) An apparatus according to Claim 28, wherein a lid of the pod is arranged in a bottom of the pod.

33. (Previously Presented) An apparatus according to Claim 28, wherein walls of the pod comprises the electromagnetic shield member.

34 - 40. (Canceled)

41. (Currently Amended) An improved pod ~~for attachment~~ attachable to an outside surface of a grounded electromagnetic-shielded chamber, said chamber having a door and a flange portion; around the door; on the outside surface and containing a micro-device manufacturing apparatus ~~for processing a substrate~~, said pod including:

walls ~~for configured to containing the~~ contain a substrate and having an opening, said walls including a flange portion configured to contact the flange portion of the ~~grounded electromagnetic-shielded~~ chamber; and

a lid ~~for an~~ configured to openably close the opening, defined by said walls, through which the substrate is being transferred between said pod and the ~~grounded electromagnetic-shielded~~ chamber through the opening, the improvement comprising:

an electromagnetic shield member, said electromagnetic shield member ~~covering~~ being arranged over said walls and ~~arranged on said~~ the flange portion of said walls, said

electromagnetic shield member on the flange portion of said walls being configured to contact the grounded flange portion of the chamber while said pod is attached to the outside surface.

42. (Previously Presented) A pod according to Claim 41, wherein said lid is arranged in a front of said pod.

43. (Previously Presented) A pod according to Claim 41, wherein said lid is arranged in a bottom of said pod.

44. (Previously Presented) A pod according to Claim 41, wherein said electromagnetic shield member comprises wire mesh arranged on or within said walls.

45. (Previously Presented) A pod according to Claim 41, wherein said electromagnetic shield member comprises metal coatings arranged on said walls.

46. (Previously Presented) A pod according to Claim 41, wherein said electromagnetic shield member comprises electromagnetic-shield materials arranged in said walls.

47. (Currently Amended) An improved micro-device manufacturing apparatus for ~~processing a substrate, said apparatus~~ including:

a grounded electromagnetic-shielded chamber having a door and a flange portion;
around said door[[,]] on an outside surface of said ~~grounded electromagnetic-shielded~~ chamber;

a transfer unit; arranged in said ~~grounded electromagnetic-shielded~~ chamber[[,]] and
configured to transfer ~~the~~ a substrate between said ~~grounded electromagnetic-shielded~~ chamber
and a pod, the pod being attached to the outside surface and having an electromagnetic shield
member which includes a flange portion configured to contact said flange portion of said
~~grounded electromagnetic-shielded~~ chamber; and

a processing unit; arranged in said ~~grounded electromagnetic-shielded~~ chamber;
and configured to process the substrate transferred into said ~~grounded electromagnetic-shielded~~
chamber from the pod by said transfer unit, improved in that:

said flange portion of said ~~grounded electromagnetic-shielded~~ chamber is grounded
and configured to contact the flange portion of the electromagnetic shield member of the pod
while the pod is attached to the outside surface.

48. (Currently Amended) An apparatus according to 47, wherein said transfer unit
is configured to transfer the substrate between said ~~grounded electromagnetic-shielded~~ chamber
and the pod through said door.

49. (Previously Presented) An apparatus according to 47, wherein said processing
unit is configured to expose the substrate to a pattern.

50. (Previously Presented) An apparatus according to Claim 47, wherein a lid of the pod is arranged in a front of the pod.

51. (Previously Presented) An apparatus according to Claim 47, wherein a lid of the pod is arranged in a bottom of the pod.

52. (Currently Amended) An apparatus according to Claim 47, wherein the pod includes walls ~~for~~ configured to containing the substrate and having an opening, and a lid ~~for an~~ configured to openably close the opening, defined by the walls, through which the substrate is being transferred by said transfer unit through the opening, the walls including the flange portion of the pod, ~~an~~ the electromagnetic shield member ~~covering~~ being arranged over the walls and ~~arranged~~ on the flange portion of the walls.